

SSCL022N40GN6

N-Channel Enhancement Mode MOSFET

> Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	l _D
40V	+20V	2.2 mΩ@10V	1204
	<u> </u>	3 mΩ@4.5V	130A

> Description

This device is N-Channel enhancement MOSFET.

Uses SGT technology and design to provide excellent

RDSON with low gate charge. This device is suitable
for use in DC-DC conversion, power switch and
charging circuit.

100% UIS + ΔVDS + Rg Tested!

Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

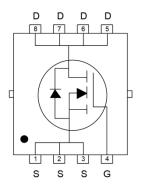
Ordering Information

Device	Package	Shipping
SSCL022N40GN6	PDFN5X6-8L	5000/Reel

> Pin Configuration



PDFN5X6-8L (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)



➤ Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit	
V_{DSS}	Drain-to-Source Voltage		40	V
V _{GSS}	Gate-to-Source Volta	ge	±20	V
	VGSS Gate-to-Source Voltage ID Continuous Drain Current d $T_C=25^{\circ}C$ $T_C=100^{\circ}C$ $T_A=25^{\circ}C$ TA=25^{\circ}C $T_A=70^{\circ}C$ IDM Pulsed Drain Current downship To	130	۸	
ID	Continuous Drain Current	T _C =100℃	82	- A
,	Continuous Drain Current ^a T _A =70 °C	25	^	
IDSM		T _A =70°C	21	A
I _{DM}	Pulsed Drain Current	Pulsed Drain Current b		А
Б	D D: : #: 0	Tc=25°C	83	W
Pb	Power Dissipation •	oltage $T_{C}=25^{\circ}C$ $T_{C}=100^{\circ}C$ $T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$ Tent b $T_{C}=25^{\circ}C$ $T_{C}=100^{\circ}C$ $T_{A}=25^{\circ}C$ $T_{A}=70^{\circ}C$ H Single Pulse H Single Pulse hperature	33	
D	Davis Diaging time 2	T _A =25°C	3.1	107
PDSM	Power Dissipation ^a	T _A =70°C	2.0	W
las	Avalanche Current ^b L=0.5mH Single Pulse		24	Α
Eas	Avalanche Energy ^b L=0.5mH Single Pulse		144	mJ
TJ	Operation junction temperature		-55~150	°C
T _{STG}	Storage temperature ra	inge	-55~150	${\mathbb C}$

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Max.	Unit
R _{θJA}	Junction-to-Ambient Thermal Resistance ^a	40	55	°C/W
$R_{ heta JC}$	Junction-to-Case Thermal Resistance	1.5	2.0	C/VV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

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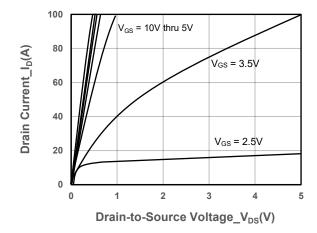
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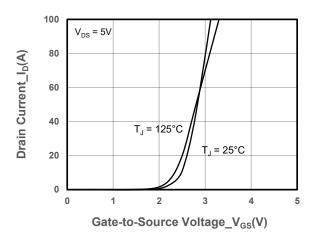
➤ Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	40			V
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250$ uA	1.0	1.6	2.5	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		2.2	3	mΩ
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 4.5V, I _D = 10A		3	4.3	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	Igss	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Transconductance	G _{FS}	V _{DS} = 5V, I _D = 10A		38		S
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 10A		0.8	1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		1.2		Ω
Input Capacitance	Ciss	V - 00V V - 0V		2070		
Output Capacitance	Coss	$V_{DS} = 20V, V_{GS} = 0V,$		1125		pF
Reverse Transfer Capacitance	Crss	f = 1MHz		40		
Total Gate Charge	Q _G	10// 20//		32		
Gate to Source Charge	Q _G s	V _{GS} = 10V, V _{DS} = 20V,		6.5		nC
Gate to Drain Charge	Q _{GD}	I _D = 20A		6		
Turn-on Delay Time	T _{D(ON)}			15		
Rise Time	Tr	V _{GS} = 10V, V _{DS} = 20V,		6		
Turn-off Delay Time	$T_{D(OFF)}$	$I_D = 20A, R_G = 3\Omega$		43		ns
Fall Time	T _f			12		
Diode Recovery Time	Trr	I _F =20A, di/dt=100A/us		66		ns
Diode Recovery Charge	Qrr	I _F =20A, di/dt=100A/us		15		nC

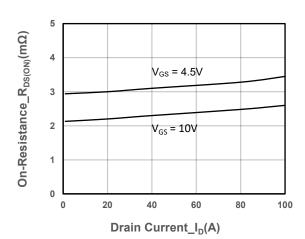


➤ Typical Performance Characteristics (T_A=25°C unless otherwise noted)

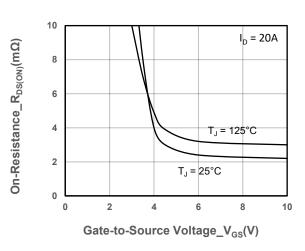




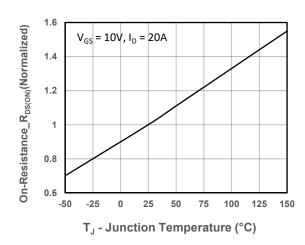
Output Characteristics



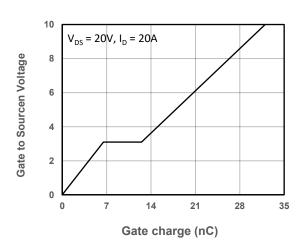
Transfer Characteristics



On-Resistance vs. Drain Current and Gate Voltage



On-Resistance vs. Gate-to-Source Voltage

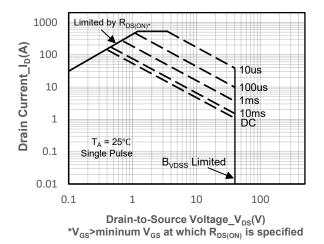


On-Resistance vs. Junction Temperature

Gate-Source Voltage vs. Gate charge

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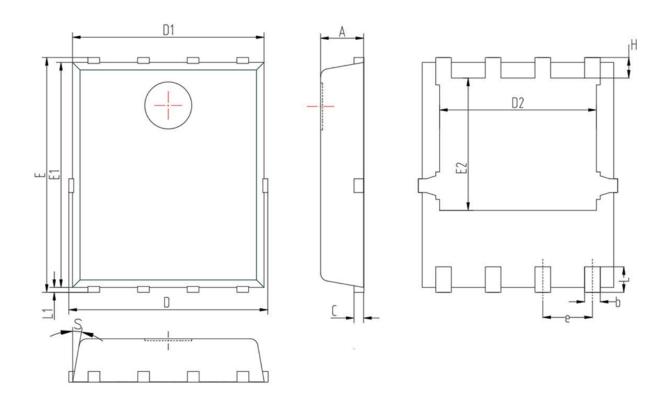




Safe Operating Area vs. Junction-to-Ambient



Package Information



Symbol	MILL IMETER			
	Min	Nom	Max	
А	0.90	1.05	1.20	
b	0.25	0.30	0.51	
С	0.15	0.25	0.35	
D	4.80	5.10	5.40	
D1	4.80	5.00	5.20	
D2	3.70	4.00	4.30	
E	5.80	6.15	6.50	
E1	5.50	5.75	5.95	
E2	3.30	3.45	3.67	
е	1.27BSC			
Н	0.40	0.60	0.93	
L	0.45	0.65	0.85	
L1	0.00	0.10	0.25	
S	0°		12°	



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